

# **FPN530** FPN530A



## **NPN Low Saturation Transistor**

These devices are designed for high current gain and low saturation voltage with collector currents up to 3.0 A continuous. Sourced from Process NC.

#### **Absolute Maximum Ratings\*** TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	30	V
V <sub>CBO</sub>	Collector-Base Voltage	60	V
V <sub>EBO</sub>	Emitter-Base Voltage	5.0	V
Ic	Collector Current - Continuous	3.0	A
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### **Thermal Characteristics** TA = 25°C unless otherwise noted

Symbol	Characteristic	Max	Units
		FPN530 / FPN530A	
$P_D$	Total Device Dissipation	1.0	W
R <sub>θJC</sub>	Thermal Resistance, Junction to Case	50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	125	°C/W

NOTES:

1) These ratings are based on a maximum junction temperature of 150 degrees C.

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

## **NPN Low Saturation Transistor**

(continued)

Min Max Units

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**Parameter** 

TA = 25°C unless otherwise noted

**Test Conditions** 

OFF CHAI	RACTERISTICS				
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	$I_C = 10 \text{ mA}, I_B = 0$	30		V
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 100  \mu A,  I_E = 0$	60		V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 100  \mu A,  I_C = 0$	5.0		V
I <sub>CBO</sub>	Collector Cutoff Current	$V_{CB} = 30 \text{ V}, I_{E} = 0$		100	nA
		$V_{CB} = 30 \text{ V}, I_{E} = 0, T_{A} = 100^{\circ}\text{C}$		10	μΑ
I <sub>EBO</sub>	Emitter Cutoff Current	$V_{EB} = 4.0 \text{ V}, I_{C} = 0$		100	nA

## ON CHARACTERISTICS\*

Symbol

h <sub>FE</sub>	DC Current Gain	$I_C = 100 \text{ mA}, V_{CE} = 2.0 \text{ V}$	530	100		
			530A	250		
		$I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V}$		120		
		$I_C = 2.0 \text{ A}, V_{CE} = 2.0 \text{ V}$		80		
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$I_C = 1.0 \text{ A}, I_B = 100 \text{ mA}$	530		300	mV
()			530A		250	mV
		$I_C = 2.0 \text{ A}, I_B = 200 \text{ mA}$			450	mV
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage	$I_C = 1.0 \text{ A}, I_B = 100 \text{ mA}$			1.25	V
V <sub>BE(on)</sub>	Base-Emitter Saturation Voltage	$I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V}$			1.0	V

## SMALL SIGNAL CHARACTERISTICS

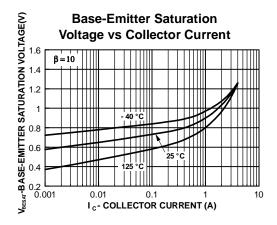
Cobo	Output Capacitance	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1.0 \text{ MHz}$		50	pF
FT	Transition Frequency	$I_C = 100 \text{ mA}, V_{CE} = 5.0 \text{ V},$ f = 100  MHz	150		MHz

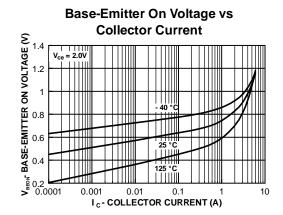
<sup>\*</sup>Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%

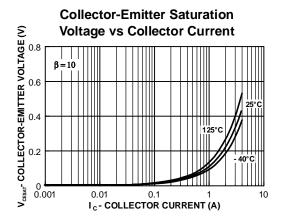
## **NPN Low Saturation Transistor**

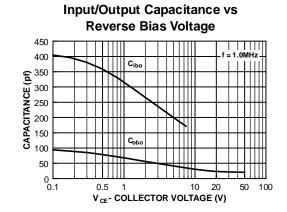
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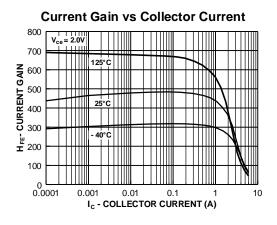
## **Typical Characteristics**

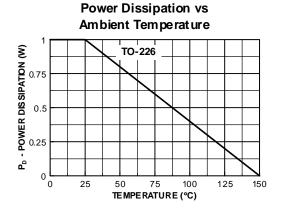












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#### **Definition of Terms**

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